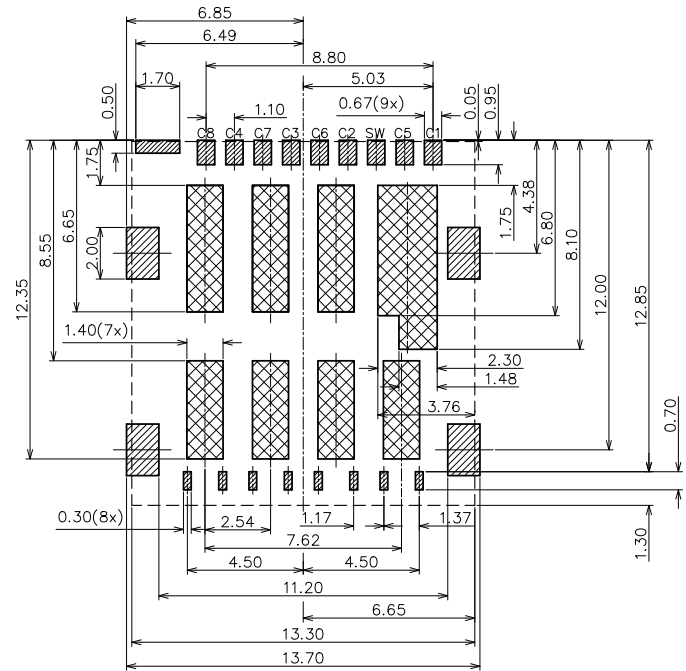
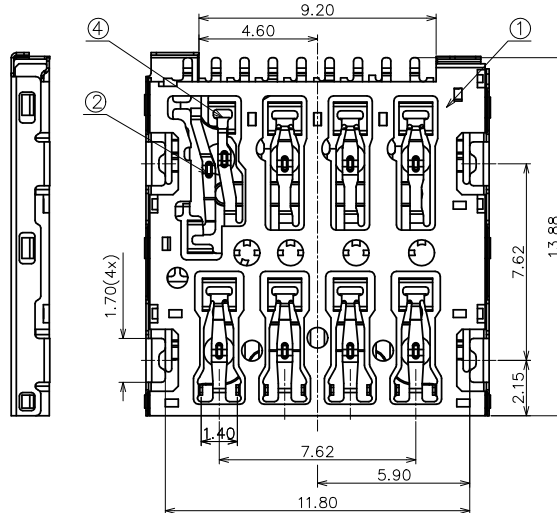
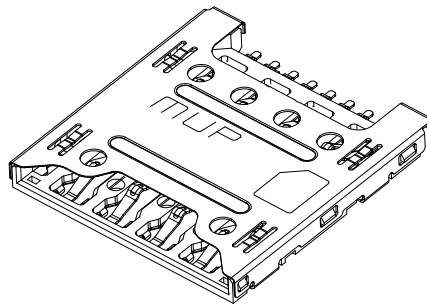
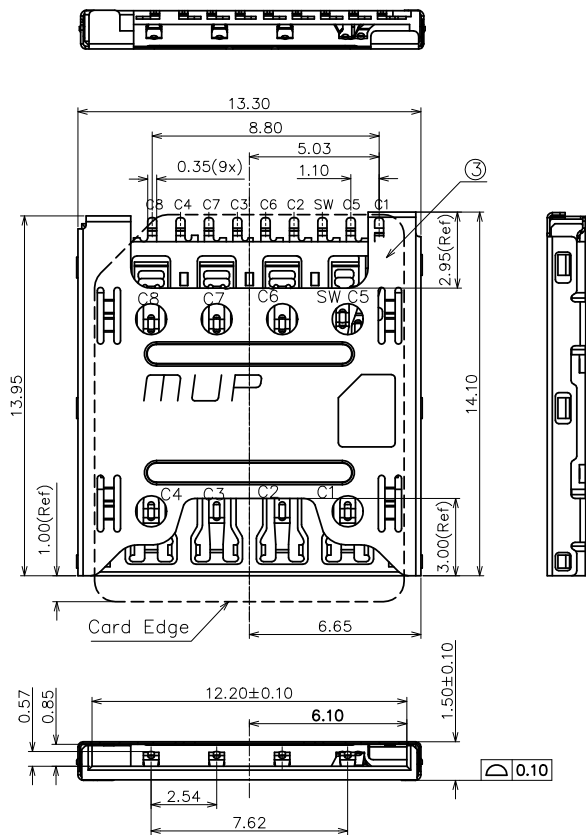


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1	NEW REVISION				Jan.03.2017
X2					



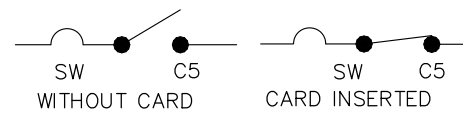
RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)

- PAD AREA
- CONNECTOR OUTLINE
- NO PATTERN AND VIA HOLE IN THIS AREA

TECHNICAL CHARACTERISTICS
 1.General Characteristics
 Dimensions:14.10LX13.30WX1.50H mm
 Weight:Approx 0.60±0.2g
 Durability:2,000 cycles min.
 2.Electrical Characteristics
 Contact resistance:50mΩ typical,
 100mΩMax
 Insulation resistance:>1000MΩ/500V DC
 3.Solderability
 Vaporphase:215°C, 30sec.Max
 IR reflow:260°C,5sec.Max
 Manual soldering:370°C.3sec.Max
 4.Environmental Characteristics
 Operating temperature:-40°C~+85°C
 Operating humidity:10%~+95%RH

Micro SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

ELECTRIC FUNCTION	DETECT SWITCH
WITHOUT CARD	OPEN
CARD INSERTED	CLOSED



SWITCH OPERATION DIAGRAM

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	8	Copper Alloy	Contact area:Gold plated
3	SW	1	Copper Alloy	Contact area:Gold plated
4	SHELL	1	Stainless Steel	Solder area:Gold plated

Unless otherwise specified, other tolerance are:

X	±0.35	X'	±5'
X.X	±0.25	X.X'	±4'
X.XX	±0.15	X.XX'	±3'
X.XXX	±0.10	X.XXX'	±2'

MUP MUP INDUSTRIAL CO.,LTD.

NAME: **Micro SIM Card Connector**

MODEL NO: **MUP-C793-1**

TYPE: **H1.50mm 8PIN**

PROJ.	UNIT	SCALE	DRAWN	DWG NO.:
	mm	1:1	Henry Jan.03.2017	DWG-MUP-C793-1
CUSTOMER DRAWING			CHECKED	SHEET
			Simon Jan.03.2017	1/1
			APPROVAL	REVISION
				X1

